



H1'23

FINANCIAL RESULTS

November 24th, 2022

DISCLAIMER

This document is provided by Soitec (the “Company”) for information purposes only.

The Company’s business operations and financial position are described in the Company’s 2021-2022 Universal Registration Document (which notably includes the 2021-2022 Annual Financial Report) which was filed on June 20th, 2022 with the French stock market authority (Autorité des Marchés Financiers, or AMF) under number D.22-0523 as well as in the Company’s FY’23 half-year report released on November 23rd, 2022. The French versions of the 2021-2022 Universal Registration Document and of the half-year report, together with English courtesy translations for information purposes of both documents are available for consultation on the Company’s website (www.soitec.com), in the section Company - Investors -

Financial Reports.

Your attention is drawn to the risk factors described in Chapter 2.1 of the Company’s 2021-2022 Universal Registration Document.

This document contains summary information and should be read in conjunction with the 2021-2022 Universal Registration Document and the FY’23 half-year report.

This document contains certain forward-looking statements. These forward-looking statements relate to the Company’s future prospects, developments and strategy and are based on analyses of earnings forecasts and estimates of amounts not yet determinable. By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events and are dependent on circumstances that may or may not materialize in the future. Forward-looking

statements are not a guarantee of the Company’s future performance. The occurrence of any of the risks described in Chapter 2.1 of the Universal Registration Document may have an impact on these forward looking statements. In addition, the future consequences of geopolitical conflicts, in particular the Ukraine / Russia situation, as well as rising inflation, may result in greater impacts than currently anticipated in these forward looking statements.

The Company’s actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company’s financial position, results, cash-flows and the developments in the sector in which the Company operates were

to conform to the forward-looking statements contained in this document, such elements cannot be construed as a reliable indication of the Company’s future results or developments.

The Company does not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document. In addition, the occurrence of any of the risks described in Chapter 2.1 of the Universal Registration Document may have an impact on these forward looking statements.

This document does not constitute or form part of an offer or a solicitation to purchase, subscribe for, or sell the Company’s securities in any country whatsoever. This document, or any part thereof, shall not form the basis of, or be relied upon in

connection with, any contract, commitment or investment decision.

Notably, this document does not constitute an offer or solicitation to purchase, subscribe for or to sell securities in the United States. Securities may not be offered or sold in the United States absent registration or an exemption from the registration under the U.S. Securities Act of 1933, as amended (the “Securities Act”). The Company’s shares have not been and will not be registered under the Securities Act. Neither the Company nor any other person intends to conduct a public offering of the Company’s securities in the United States.

AGENDA

#01
H1'23
HIGHLIGHTS

#02
Business
Highlights

#03
H1'23
FINANCIALS

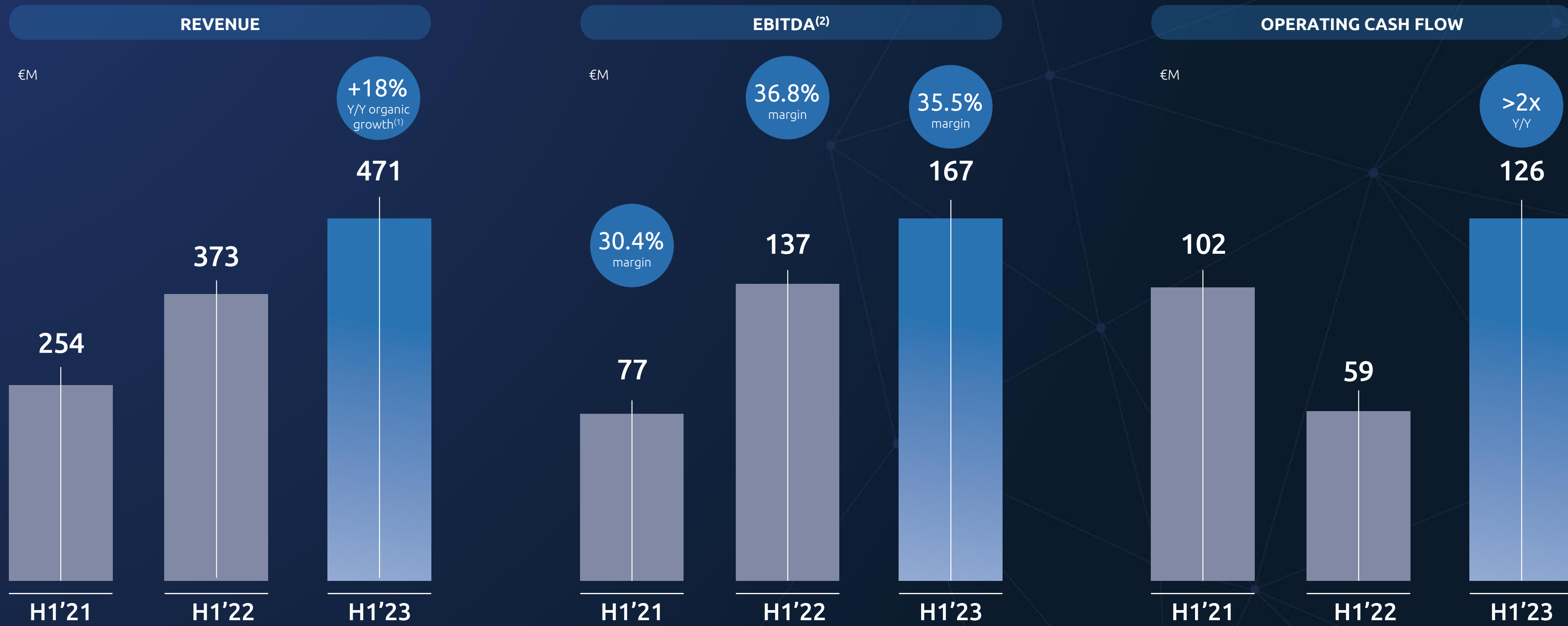
Q&A

H1'23

HIGHLIGHTS

H1'23 Key Figures

Continuing our strong profitable growth and value creation trajectory

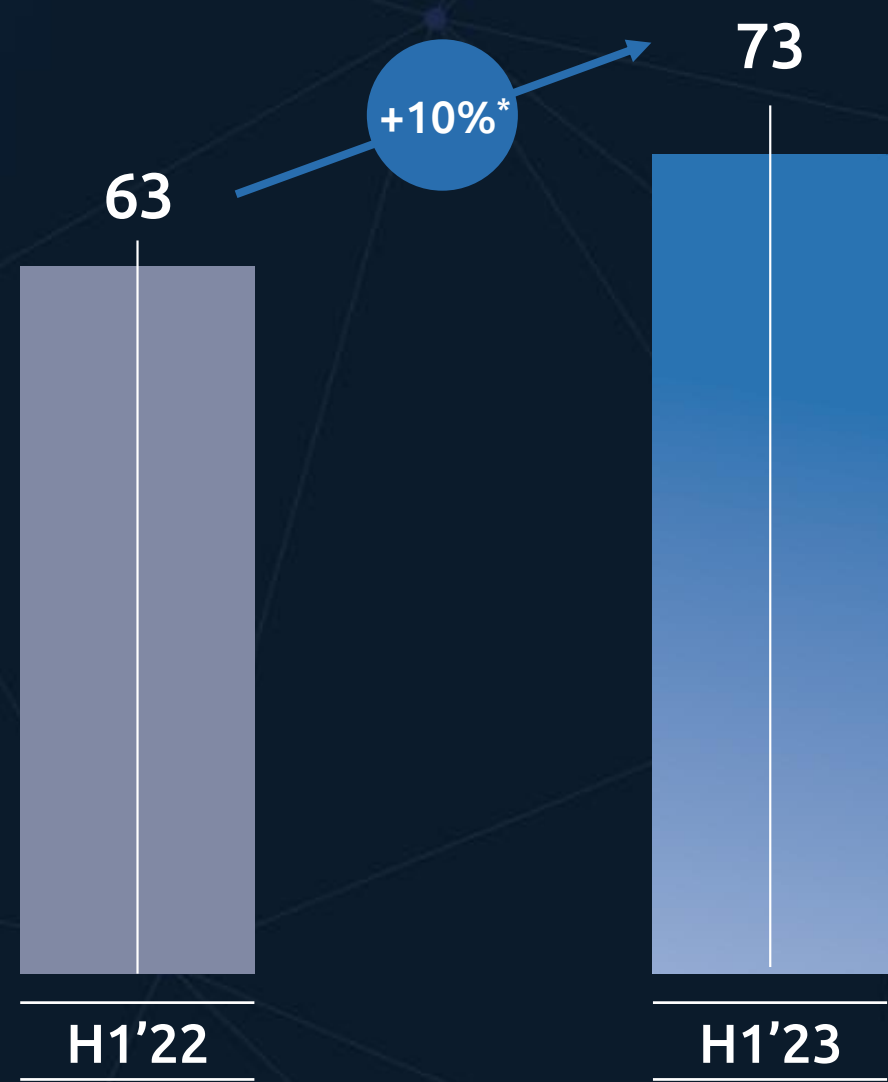
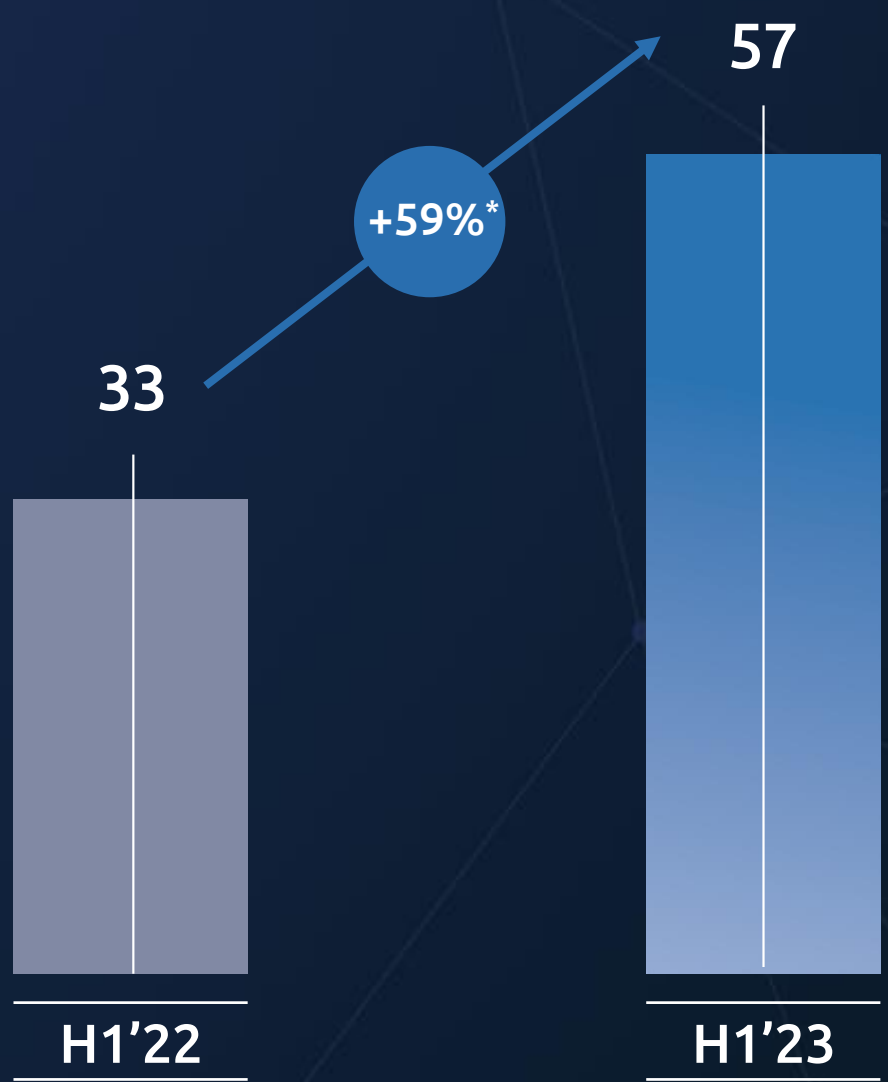
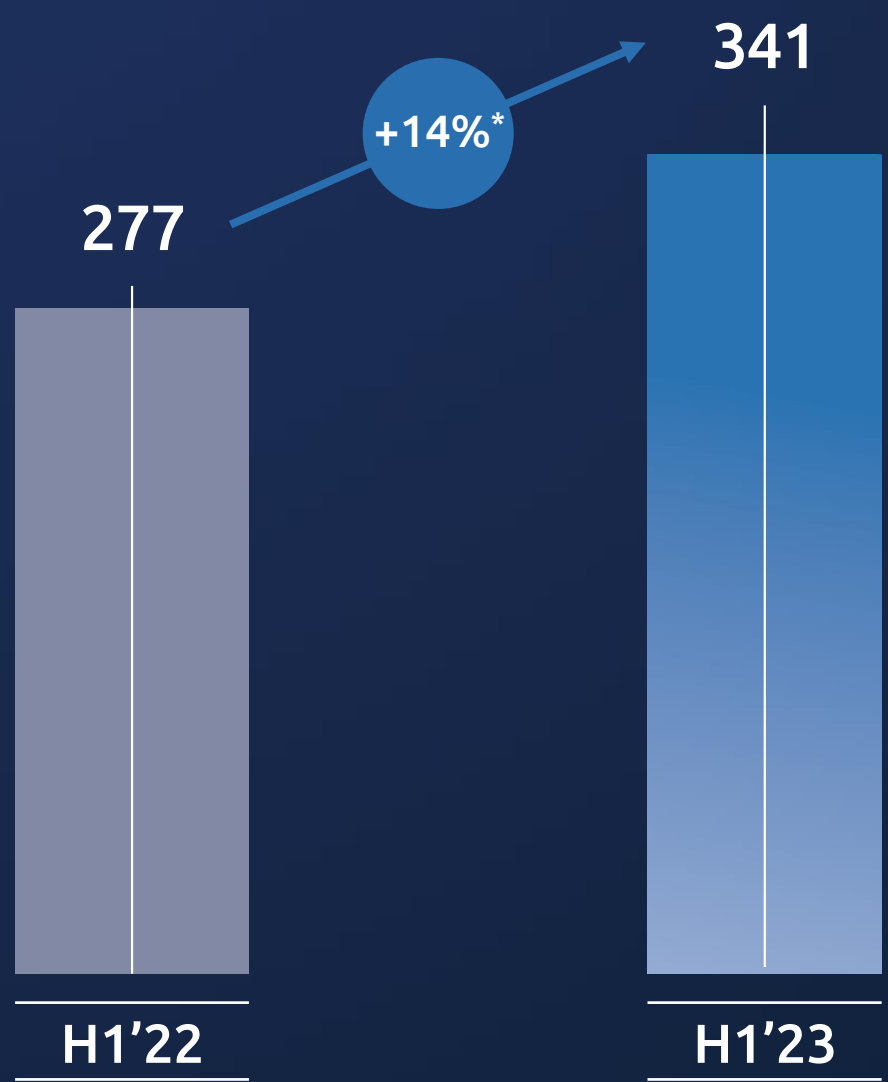


(1) At constant exchange rates and perimeter

(2) From continuing operations

H1'23 Key Figures

Strong growth confirmed across our 3 divisions



* Y/Y growth, at constant exchange rates and perimeter

CAPACITY EXPANSION FOR ALL PRODUCTS AND SECURED LTAs WITH STRATEGIC SUPPLIERS

Country	Soitec Fab	Product	Diameter	Max capacity (wafers per year)	H1'23 Highlights
FRANCE	BERNIN 1	SOI	200mm	~1Mwpy	Higher operating leverage driven by Q2'23 capacity
	BERNIN 2	SOI	300mm	~700Kwpy	Digital initiatives & process optimization driving significant yield improvement
	BERNIN 3	POI	150mm / 200mm	Raising capacity to reach ~750Kwpy	Strong activity on delivering new products. Will tune capacity addition to reflect further customer adoption
	BERNIN 4 	SiC SOI refresh	150mm / 200mm / 300mm	Building capacity to reach ~500Kwpy in phase 1	Construction on time, shell finalization in 2022. Clean room ready to move in early April 2023
SINGAPORE	PASIR RIS	SOI	300mm	Raising capacity to reach ~1Mwpy	Additional capacities implemented and qualified. Tools deliveries secured for next 18 months
	PASIR RIS EXTENSION 	SOI	300mm	Expanding capacity to reach ~1Mwpy (production starting by end FY25)	Groundbreaking expected early December
BELGIUM	HASSELT	GaN	150mm / 200mm	Raising capacity to reach ~60Kwpy	Large automated production tools qualified both for 150mm and 200mm GaN MOCVD epitaxy
CHINA	SIMGUI	SOI	200mm	~450Kwpy	Reached 450Kwpy capacity as planned

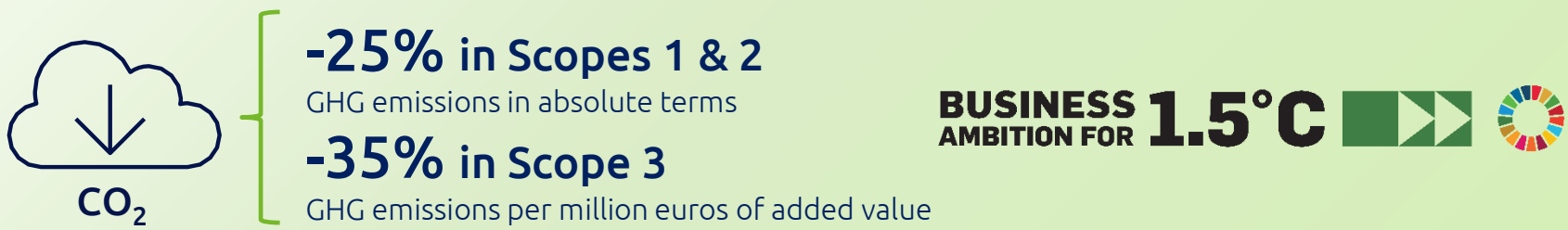
SUSTAINABILITY IS AT THE HEART OF OUR VALUE CREATION MODEL

NEW SUSTAINABILITY COMMITTEE SUPPORTING THE BOARD OF DIRECTORS

CLIMATE

Reducing our GHG emissions in our high growth context

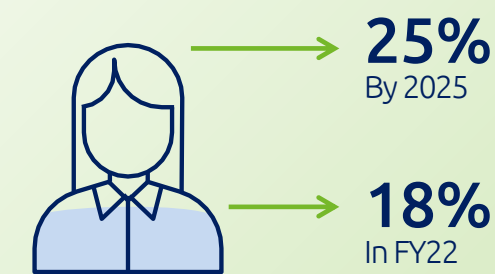
FY26 targets validated by the **Science-Based Targets initiative** (SBTi)



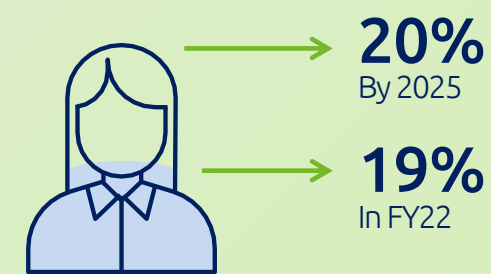
DIVERSITY AND INCLUSION

2021 SEMI Industry Leader in Diversity and Inclusion award

Increase the percentage of women in the **Executive Committee**

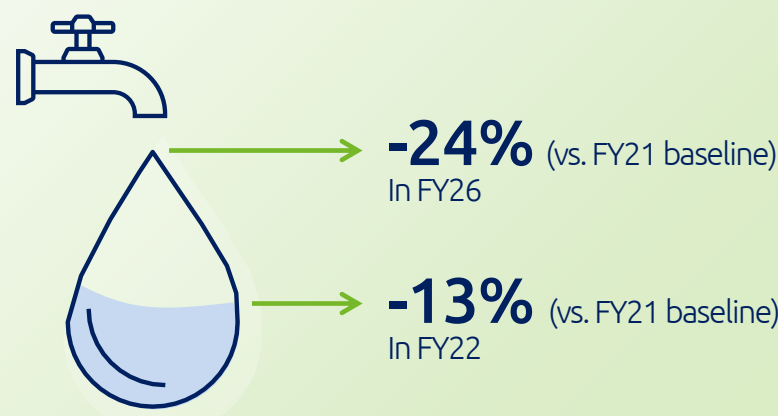


Increase the percentage of women among **senior executives**



WATER

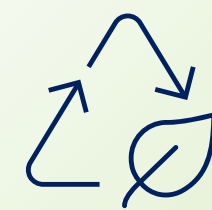
Reducing our **water consumption** per production unit



Better **recycling or reusing water** at our Bernin plant



GREENOVATION



Eco-designing our products to make smart and energy-efficient electronics growing into **sustainable life experiences**



A COMMITTED AND TALENTED MANAGEMENT TEAM DRIVING OUR NEW ORGANIZATION TO EXECUTE OUR AMBITIOUS GROWTH PLANS



**Pierre
Barnabé**
CEO



**Bernard
Aspar**
COO



**Caroline
Sasia**
Communications
& Chief of staff



**Patrick
Noonan**
Legal



**Pascal
Lobry**
People &
Sustainability



**Christophe
Maleville**
CTO



**Steve
Babureck**
Strategy &
Investor Relations



**Léa
Alzingre**
CFO



**Thomas
Piliszcuk**
Global Business



**Cyril
Menon**
Global Supply



**Yvon
Pastol**
Customer Group



**Reiner
Breu**
Quality



**Philippe
Pellegrin**
Global Sourcing
& Procurement

H1'23 GOVERNANCE HIGHLIGHTS

- Appointment of Pierre Barnabé – CEO
- Appointment of Caroline Sasia – Communications & Chief of staff
- New Board of Directors with improved independence level and diversity



2022 Business Highlights



MOBILE COMMUNICATIONS

H1'23 Highlights

Sub-6GHz smartphones – RF Front-End Module, WiFi, UWB

Connect RF-SOI leadership in RFFE confirmed:

- Securing increasing technology market share in cellular, WiFi and UWB FEs
- Partnering with top foundries globally to develop the next generation of CMOS on RF-SOI platforms for next generation 5G and Wi-Fi

Connect FD-SOI: high volume production for Envelope Tracker

Connect POI adoption phase ongoing, addressing a diverse range of module architectures:

- High level of activity with several customers confirms the added value of our POI wafers for filters

mmWave Smartphones

- Connect FD-SOI endorsed by major players
- Solutions for mmWave Antenna Modules built on Connect FD-SOI embedded in handsets on the market

5G infrastructure and SatCom

- Connect RF-SOI secured market share for sub-6GHz switches and other functions
- Connect RF-SOI confirmed as technology of choice for 5G mmWave infrastructure with several design wins
- Connect FD-SOI embedded in Satellite Internet Constellation and Ground station products
- 150mm Connect RF-GaN under qualification with several customers

End Market Dynamics

High-single digit decline for global smartphones in 2022

- ~650 M 5G smartphones, confirming ~50% 5G penetration

Product Portfolio

Main Drivers

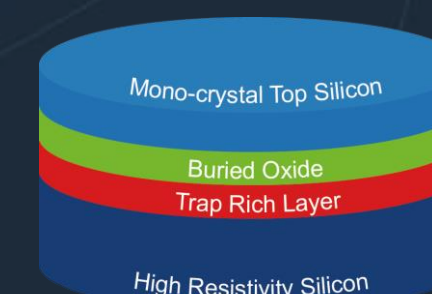
5G Sub-6GHz

5G mmWave

Mobile Infrastructure

WiFi 6, 6E & 7 / UWB

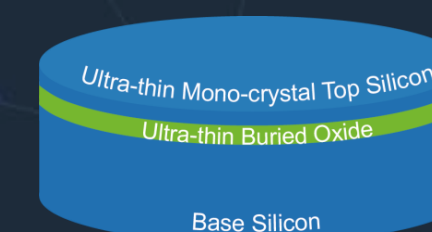
Connect RF-SOI
For highly efficient
mobile communications



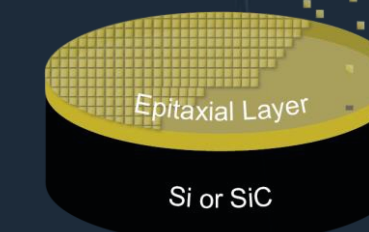
Connect POI
High performance
5G filters



Connect FD-SOI
Integrated
technology

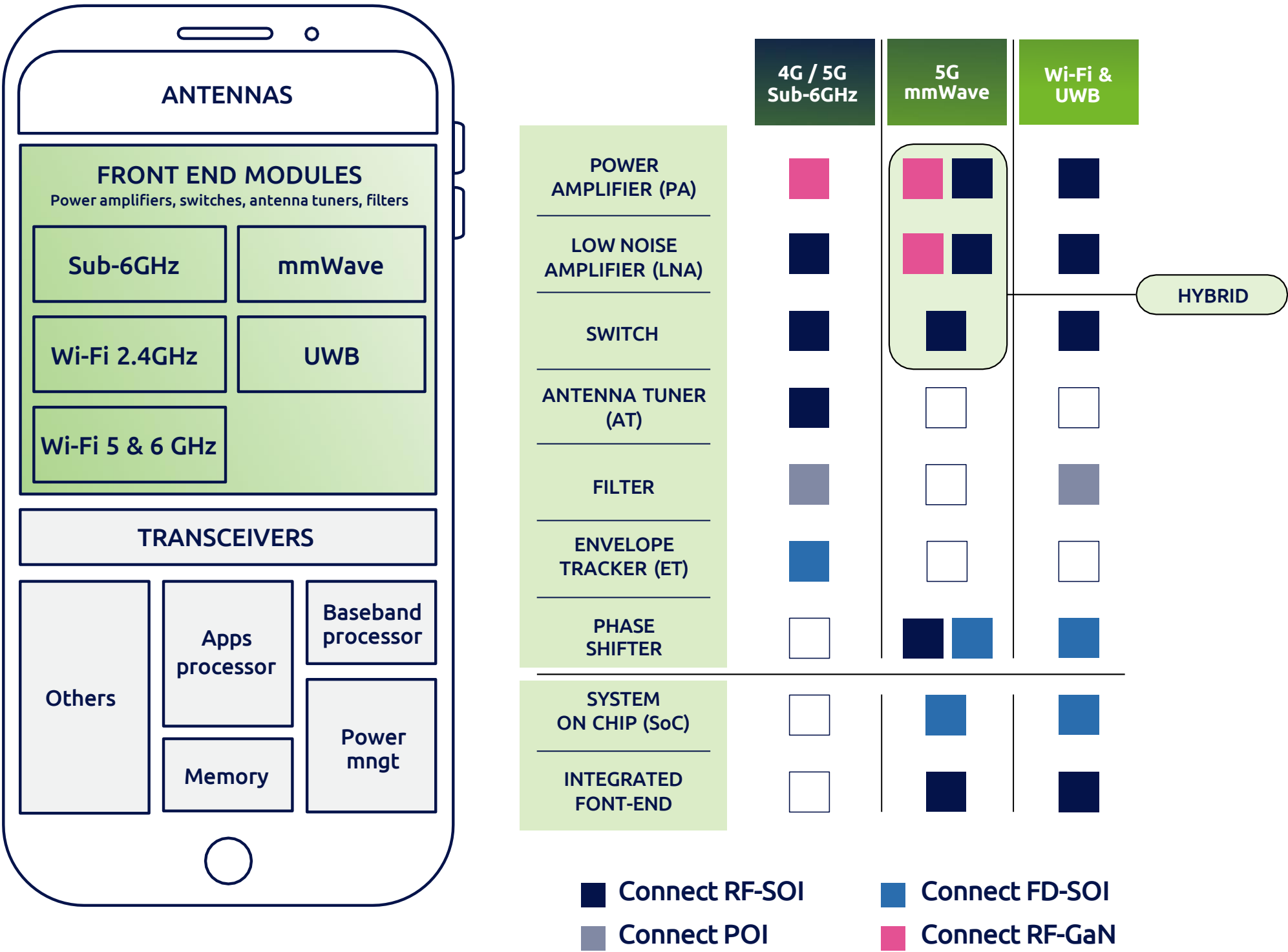


Connect RF-GaN
High performance
Power amplifiers



SOITEC PRODUCTS ENABLE BEST-IN-CLASS CONNECTIVITY

A COMPREHENSIVE OFFER FOR Sub-6GHz AND mmWave FRONT END MODULES



ENGINEERED SUBSTRATES FOR Sub-6GHz

Soitec offers best-in-class RF Front End technologies:

- **Connect RF-SOI** based on our technology embedded in 100% of smartphones
- **Connect POI** for high performance 5G filters
- **Connect RF-GaN** for extended 5G Sub-6GHz ultra high band
- **Connect FD-SOI** for 5G broadband envelope tracker

ENGINEERED SUBSTRATES FOR 5G mmWave ADOPTION

Soitec offers a complete engineered substrate portfolio to support multiple 5G mmWave RF Front End architectures:

- Hybrid RF Front End combining *Connect RF-GaN* power amplifier best-in-class efficiency with *Connect RF-SOI* LNA and switches
- Monolithic *Connect RF-SOI* mmWave RF Front End with best-in-class performance vs integration trade-off
- Full chip *Connect FD-SOI* mmWave SoC with best-in-class power efficient system integration

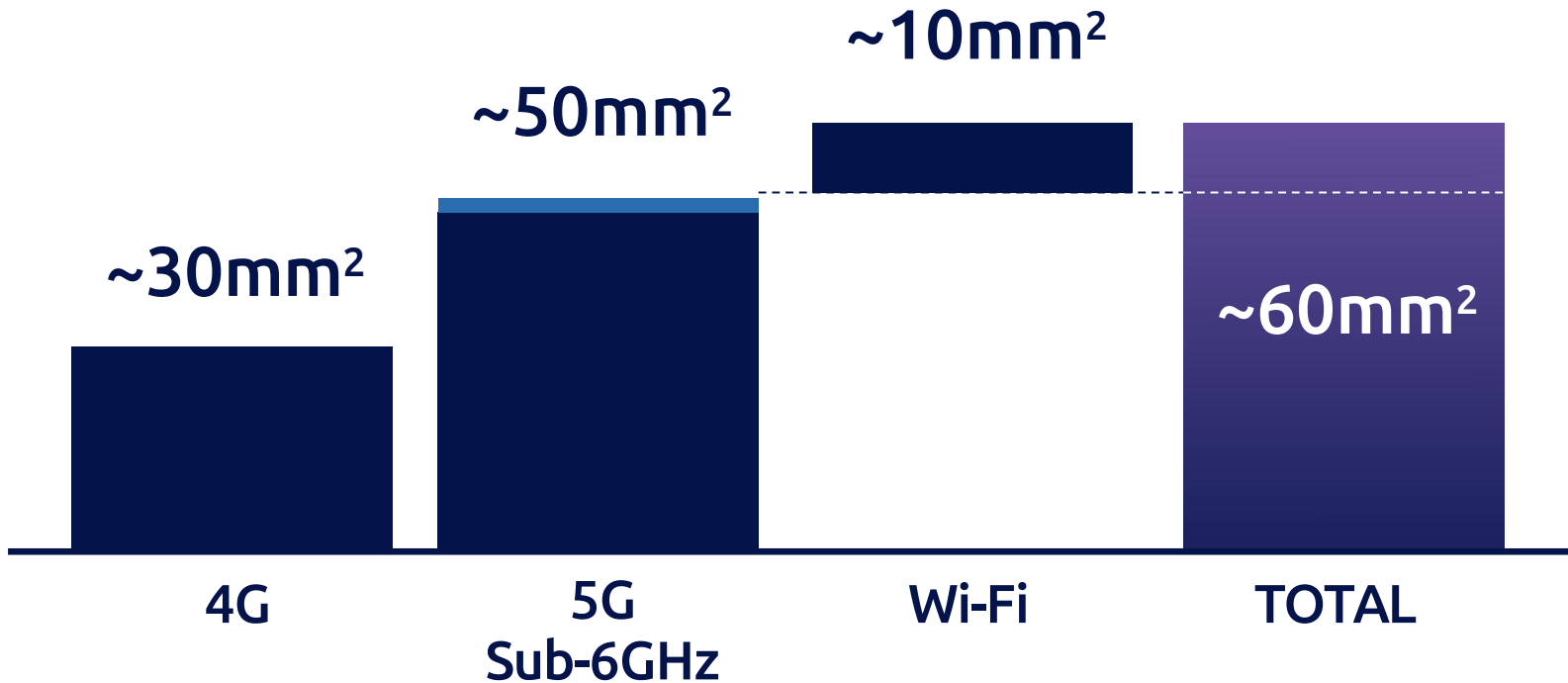
* Soitec estimates based on teardown analysis



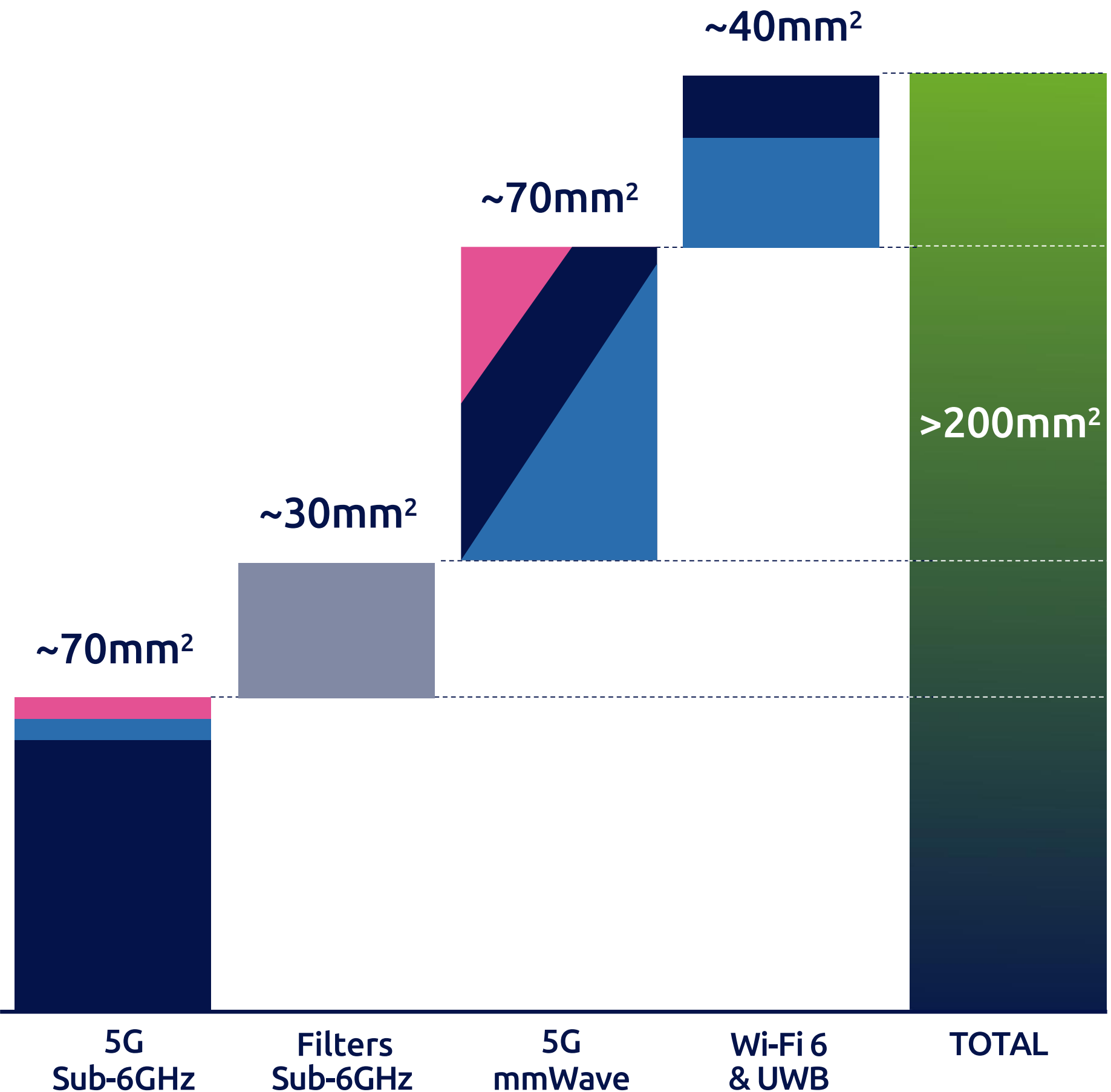
MOBILE CONTENT OPPORTUNITY IN THE NEXT FOUR YEARS IN mm^2

High-end smartphones

- Connect RF-SOI
- Connect FD-SOI
- Connect POI
- Connect RF-GaN



JUNE 2021 CMD ESTIMATES



WITHIN THE NEXT 4 YEARS





AUTOMOTIVE & INDUSTRIAL

H1'23 Highlights

Auto Power-SOI

- Robust demand for 200mm sustained by increasing functional safety content per car
- Strong demand for Power Management System and Battery Management System for Electric Vehicles
- Industry leading IC makers expanding their roadmap to 300mm
- Ongoing customer discussions to extend customer commitments duration

Auto FD-SOI

- Automotive MCU is a key adoption driver
- One of the key markets for the industrial collaboration with STMicroelectronics and GlobalFoundries
- Sustained demand for 28nm FD-SOI as a platform to drive automotive system with zonal computing
- 18nm FD-SOI and further 10-12nm development ongoing to prepare car's digitization beyond 2030
- Volume growth to address sustained demand for Radar / Lidar functions

SmartSiC™

- Demonstrated 200mm SmartSiC™ wafers, an important milestone for the market
- Progressing on Device and System qualification
- Working on 20+ projects to 10+ partners across 3 continents

Auto Power-GaN

- 200mm 650V wafers transferred to latest generation manufacturing tool

End Market Dynamics

~10%-15% growth for Automotive semiconductor in 2022

- Electric Vehicle penetration expected around ~10% of global Automotive

Source: Soitec estimates, IBS

Product Portfolio

Main Drivers

Infotainment

ADAS / Functional Safety

Electric

Industry 4.0

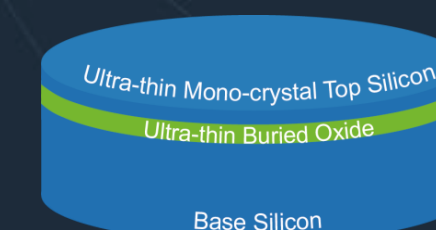
Auto Power-SOI

Power management
ICs, IVN & gate drivers



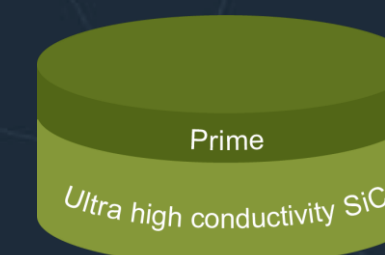
Auto FD-SOI

MCUs, ADAS-Radars
ADAS-Vision



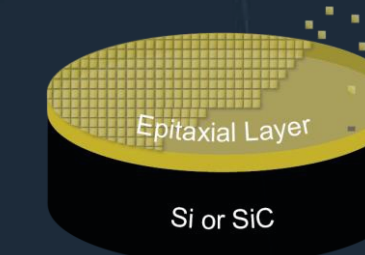
Auto SmartSiC™

Automotive
Electrification



Auto Power-GaN

DC-DC 48V
converters



SMARTSiC™

200mm DISRUPTIVE ACCELERATION FACTOR

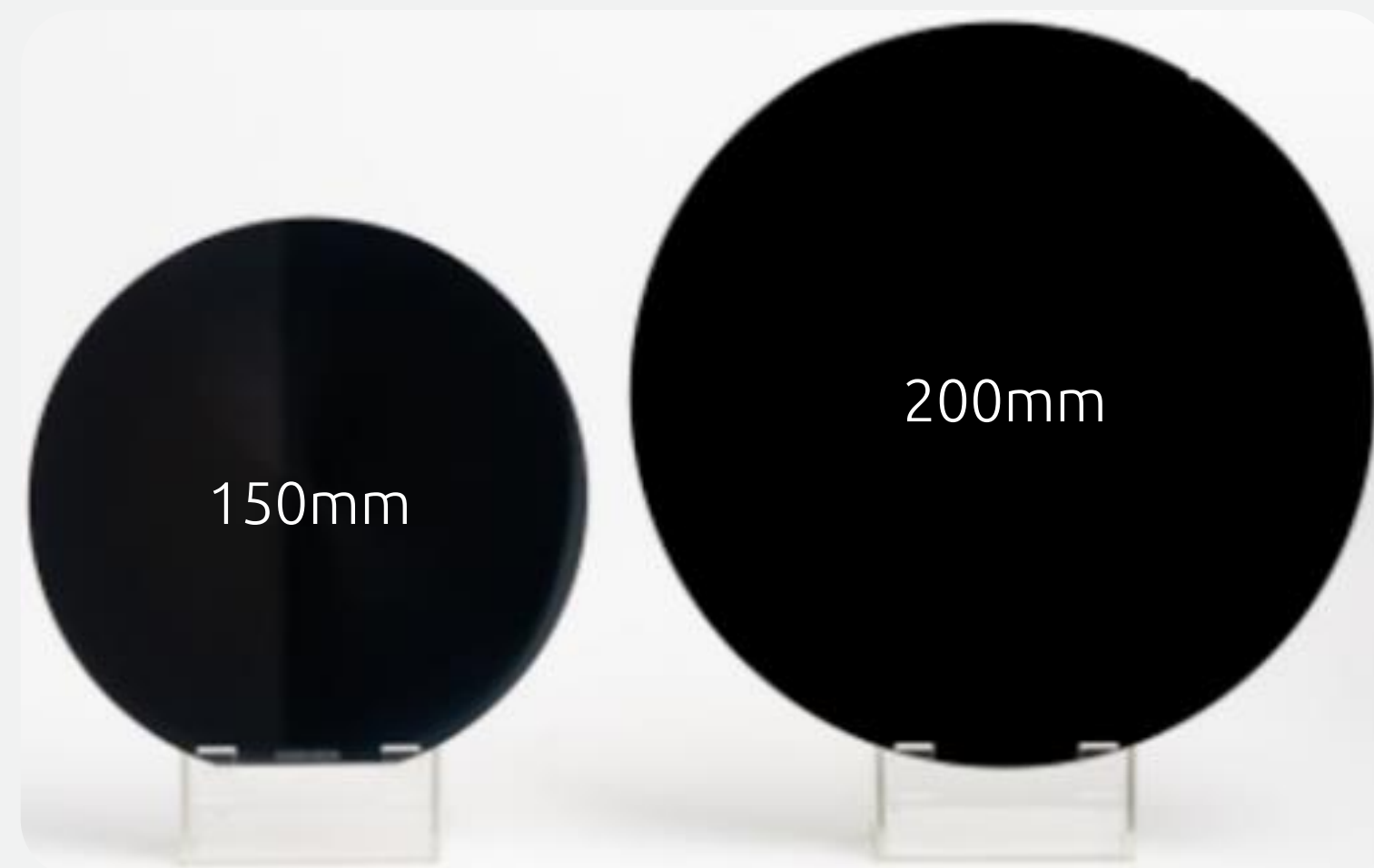
SMARTSiC™ ENABLES DEVICE MULTIPLICATION

20%

Lower Die size
SmartSiC™ enabling
more products per wafer

x1.78

Higher surface area
200mm allowing
device multiplication



200mm SMARTSiC™ FURTHER DIFFERENTIATION

200mm adds to 150mm SmartSiC™
performance improvements



Higher
yield



Better **efficiency** of
Smart Cut™ bonding



Fast **scalability**
in 200mm



Lower **cost of ownership**



SMART DEVICES

H1'23 Highlights

Smart FD-SOI

- Increasing demand for FD-SOI based Low Power computing devices (FPGAs, MCUs)
- Manufacturing collaboration between STMicroelectronics and GlobalFoundries enhancing FD-SOI technology
- STMicroelectronics launched Neural microcontroller with NPU
- Lattice FPGA integrated into Lenovo IdeaPad for AI / ML features

Smart Imager-SOI

- Ongoing strong demand driven by success on high-end smartphones

Smart Photonics-SOI

- Deployment of >400GbE transceivers in Data Centre Interconnect (200mm and 300mm)
- Industry wide collaboration to develop Silicon Photonics solutions to address data centers

Smart PD-SOI

- Skywater collaboration with Google on 90nm PD-SOI

End Market Dynamics

- Largest growth market for FD-SOI
- FD-SOI R&D activity for next generation nodes, for increased performance and density
- 3D Sensing: Solid perspectives on high-end smartphones for the next years
- Data traffic still increasing in Data centers, with faster than anticipated transition to high-speed transceivers, supported by Silicon Photonics
- Increasing momentum on Quantum computing

Product Portfolio

Main Drivers

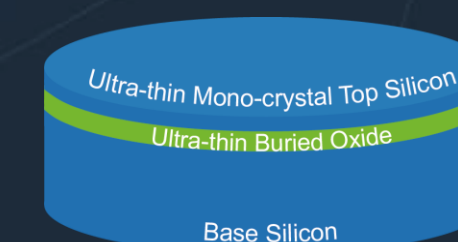
Edge Computing

Sensing

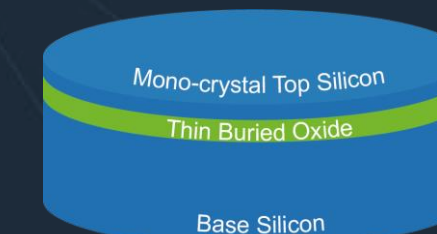
Datacenters

Metaverse

Smart FD-SOI
Crossover MCUs, connected
MCUs, scalable FPGAs



Smart Imager-SOI
For improved imager
performance in NIR



Smart Photonics-SOI
Optical transceivers
and bio-sensing

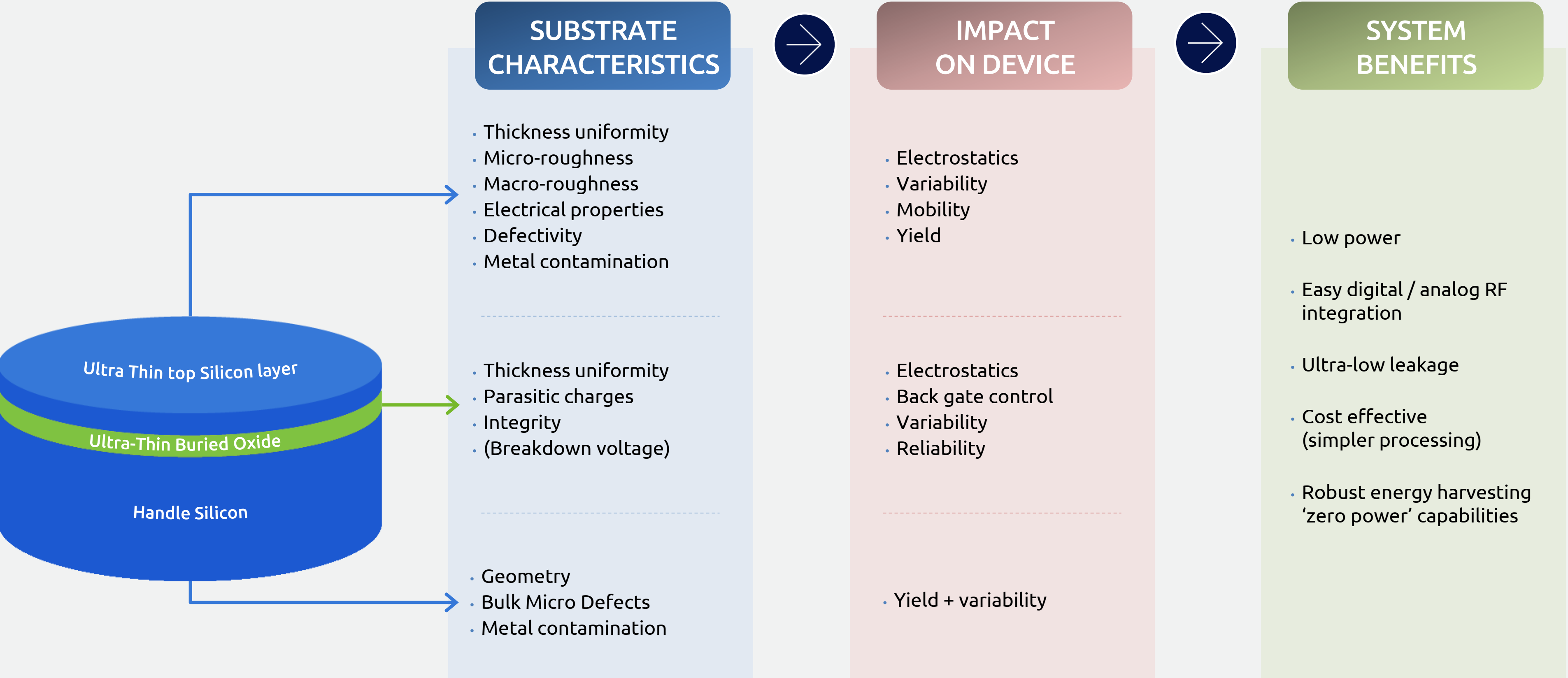


Smart PD-SOI
High performance
computing



FD-SOI

BRINGING AI ONTO THE EDGE WITH LOW ENERGY CONSUMPTION



H1'23 FINANCIALS

H1'23 – FINANCIAL HIGHLIGHTS

P&L

€471m SALES

18% YoY Organic Growth

**35.5% EBITDA⁽¹⁾
MARGIN**

-1.3pts vs H1'22

**€95M NET
PROFIT⁽²⁾**

+28% vs H1'22

€2.72 EPS

+22% vs H1'22

CASH FLOW

**€126M OPERATING
CASH FLOW⁽¹⁾**

+116% vs H1'22

€126M CAPEX

+22% vs H1'22

**€7M FREE CASH
FLOW⁽¹⁾**

up from -€43M in H1'22

BALANCE SHEET

€1.2B EQUITY

+138M vs FY22

**€743M GROSS CASH
POSITION**

+€15M vs FY22

**€113M NET CASH
POSITION**

-€29M vs FY22

(1) From continuing operations

(2) Net profit includes Net profit from continuing operations (Electronics activities) and Net profit/(loss) from discontinued operations

SOLID INCREASE IN REVENUE ACROSS ALL END-MARKETS

€M	H1'23	H1'22	Change <i>As reported</i>	Change <i>At constant FX & scope</i>
Mobile Communications	341	277	+23%	+14%
Automotive & Industrial	57	33	+72%	+59%
Smart Devices	73	63	+17%	+10%
Revenue	471	371	+26%	+18%

Mobile Communications

- Increase in RF content in every 5G smartphone led to a strong growth in RF-SOI

Automotive & Industrial

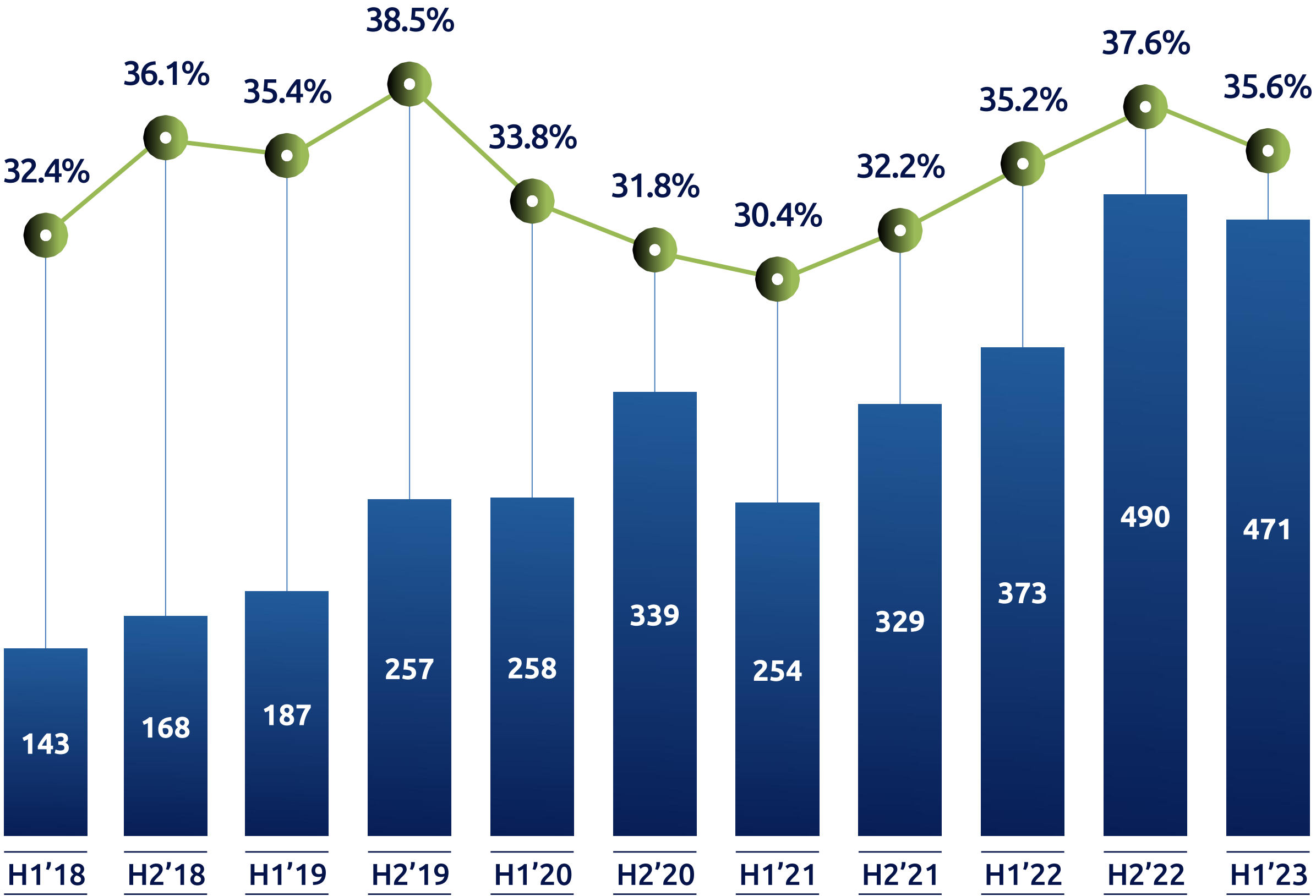
- Demand is supported by infotainment, ADAS, functional safety, EV and hybrid engines
- Sharp growth in FD-SOI
- Significant increase in Power-SOI

Smart Devices

- Demand is driven by more complex sensors, higher connectivity and embedded intelligence
- Very strong growth in FD-SOI for IoT and edge computing devices
- Sustained growth in Photonics (data centers) and Imagers (3D imaging)



GROSS MARGIN FURTHER IMPROVED TO 35.6%



+0.4
pts

- Gross margin as % in revenue
- Total revenue (€M)

GROSS MARGIN TAILWINDS

- Strong operating leverage (robust increase in activity)
- Good industrial performance despite production shutdowns in Q1

GROSS MARGIN HEADWINDS

- Dilutive currency impact
- Higher bulk material prices



CURRENT OPERATING INCOME INCREASED BY 46%

€M	H1'23	H1'22	Change
Revenue	471	371	+26%
Gross profit	168	131	+27%
as a % of revenue	35.6%	35.2%	
- Gross R&D expenses	(43)	(44)	-2%
- Prototype sales and other revenue	2	2	-11%
- Subsidies and income tax credit	12	14	-14%
Net R&D expenses	(29)	(28)	+5%
as a % of revenue	6.1%	7.4%	
- Sales and Marketing expenses	(8)	(7)	+19%
- General and Administrative expenses	(20)	(22)	-6%
SG&A expenses	(28)	(28)	-0%
as a % of revenue	6.0%	7.6%	
Current operating income	110	75	+46%
as a % of revenue	23.4%	20.2%	

Current operating margin improved by more than 3pts from 20.2% to 23.4% of revenue

- Robust Gross margin
- Tight control over SG&A expenses

Net R&D expenses down to 6.1% of revenue

- Gross R&D expenses before capitalization increased by €7m reflecting the effort to support innovation strategy and product portfolio expansion

SG&A expenses down to 6.0% of revenue

- Stable SG&A expenses despite growth and inflation
- Higher number of staff and increase in salaries
- Offset by decline in share-based compensation due to lower share price

NET PROFIT RAISED BY 28%

€M	H1'23	H1'22	Change
Current operating income	110	75	+46%
- Other operating income and expenses	0	9	
Operating income	110	85	+30%
- Financial expenses	(7)	(8)	
- Net foreign exchange gain	4	3	
Net financial result	(2)	(5)	
- Income tax	(13)	(6)	
Net profit from continuing operations	95	74	+27%
- Net profit / (loss) from discontinued operations	0	(0)	
Net profit (Group share)	95	74	+28%
- Basic EPS (in €)	2.72	2.23	+22%
- Diluted EPS (in €)	2.65	2.14	+24%
Number of shares	35,001,682	33,311,866	
Number of diluted shares	36,951,749	36,680,990	

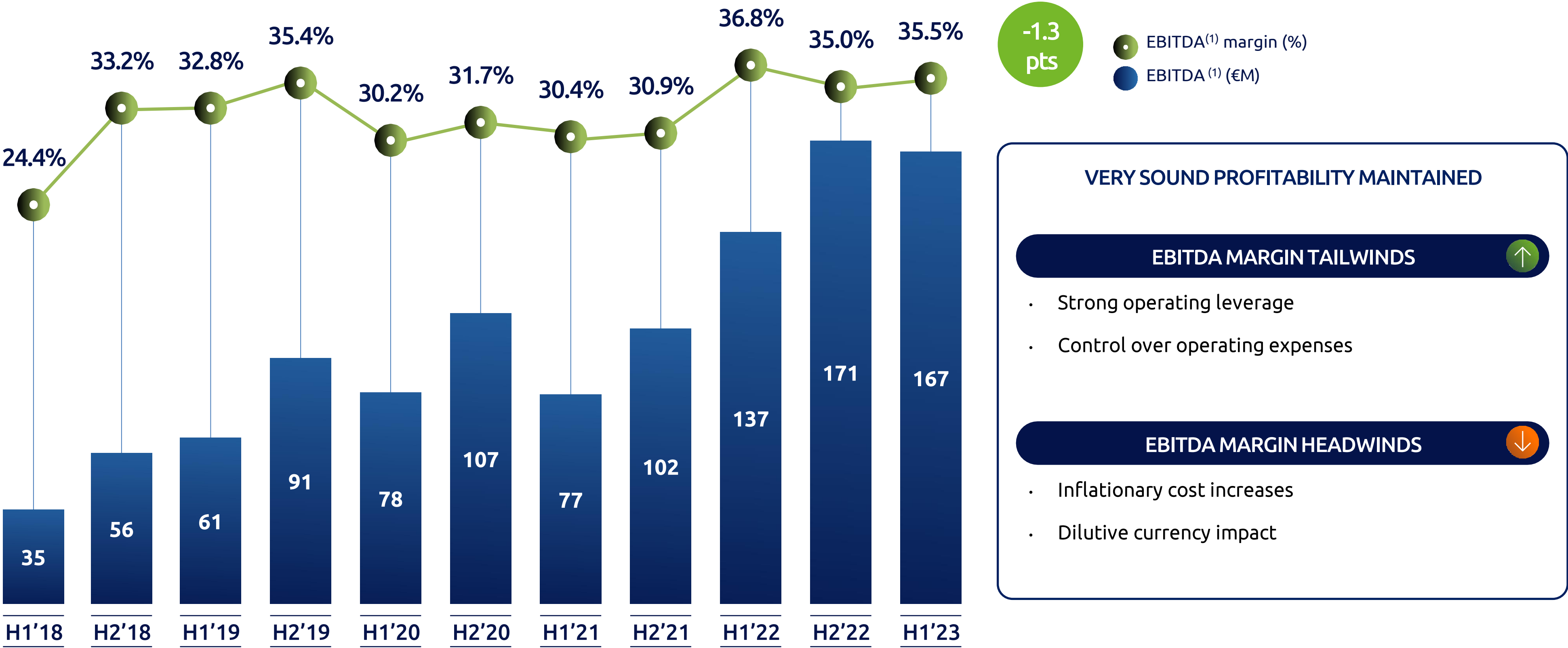
H1'22 benefitted from +€9M in other operating income reflecting the full reversal of an impairment loss related to Singapore industrial building

Net financial result at €(2)M:

- Slight decrease in financial expenses (positive impact of OCEANES 2023 conversion)
- Slightly higher net foreign exchange gain

Income tax continued to benefit from tax loss carryforwards

SUSTAINED EBITDA MARGIN AT 35.5% OF REVENUE



(1) From continuing operations



POSITIVE FREE CASH FLOW WHILE CAPACITY INVESTMENTS INCREASED FURTHER

€M	H1'23	H1'22
Operating income	110	85
- Depreciation and amortization	50	37
- Other items	7	16
EBITDA⁽¹⁾	167	137
Change in working capital	(26)	(82)
- incl. inventories	(39)	(37)
- incl. trade receivables	28	(19)
- incl. trade payables	4	7
- incl. others	(18)	(32)
- Tax paid	(15)	3
Net Cash generated by Operating activities⁽¹⁾	126	59
- Purchases Intangible assets	(20)	(13)
- Purchases of property, plant and equipment	(97)	(85)
- Others	(2)	(3)
Net cash used in Investing activities⁽¹⁾	(120)	(101)
Free Cash Flow⁽¹⁾	7	(43)

(1) From continuing operations

OPERATING CASH FLOW MORE THAN DOUBLED TO €126M

Strong improvement in net cash generated by operating activities due to increase in EBITDA and working capital management

- €39M increase in inventories to support H2'23 sales
- €15M increase in other receivables
- Offset partially by cash collection for trade receivables

€18m increase in tax paid

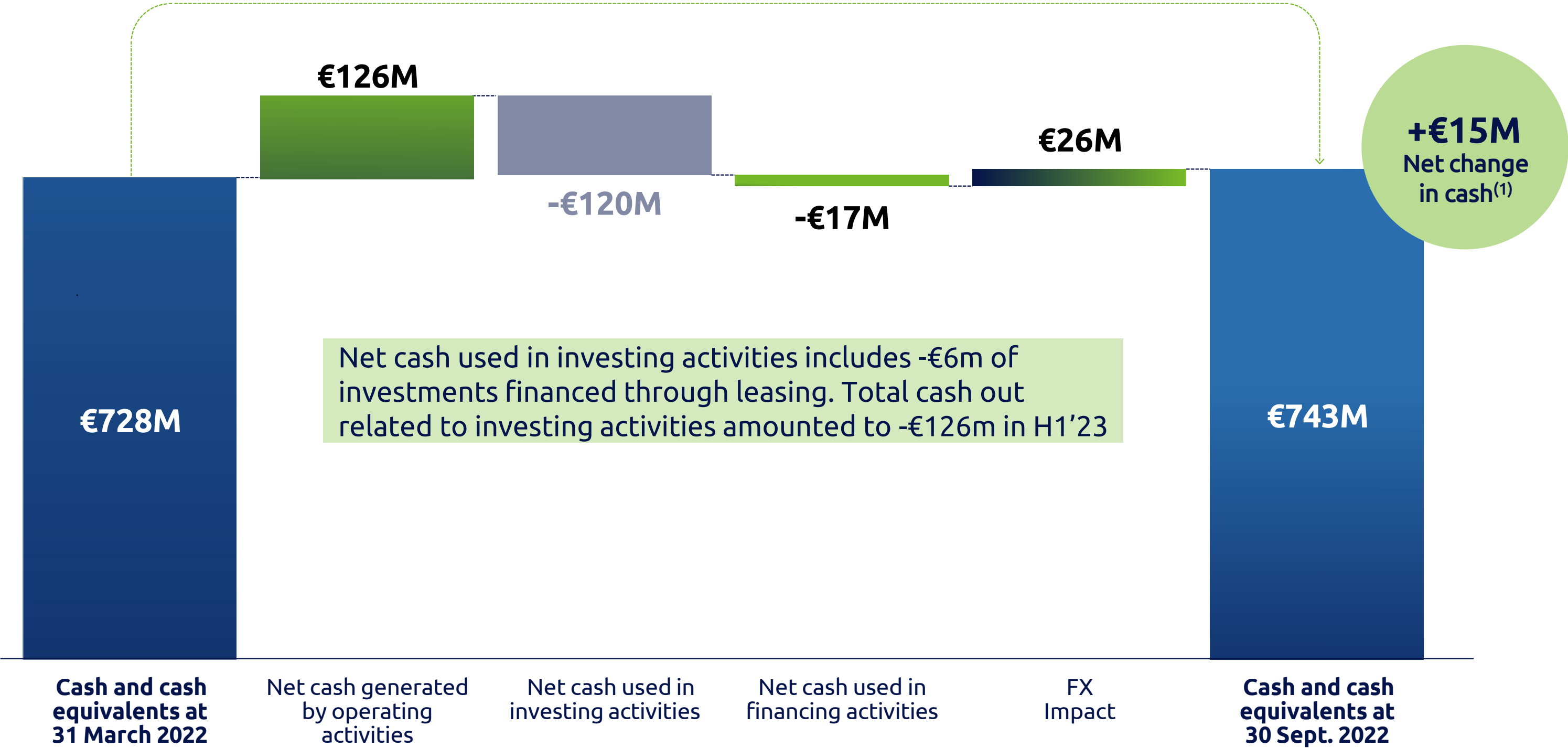
- €15M tax paid in H1'23 vs €3M net tax refund in H1'22

POSITIVE FREE CASH FLOW AT €7M vs. €(43)M in H1'22

Investments up 18% to €120M

- €15M in capitalized R&D (€8M increase vs. H1'22)
- €97M related to capacity investments mainly in Singapore (300mm including refresh and epitaxy)

STRONG CASH POSITION FURTHER IMPROVED



(1) Cash outflow related to discontinued operations was close to zero



VERY SOUND BALANCE SHEET MAINTAINED

ASSETS - in €M

	30 Sept. 2022	31 March 2022
Intangible assets	115	108
Tangible assets	648	562
Other non-current assets	39	35
Deferred tax assets	73	64
Total non-current assets	875	770
Inventories	192	143
Trade receivables	279	280
Other current assets	84	66
Cash and cash equivalents	743	728
Total current assets	1,298	1,216
Total assets	2,173	1,986

€86M net increase in tangible assets includes €83M investments related to:

- Capacity investment in Singapore 300mm SOI facility
- Capacity investment and equipment renewal in Bernin

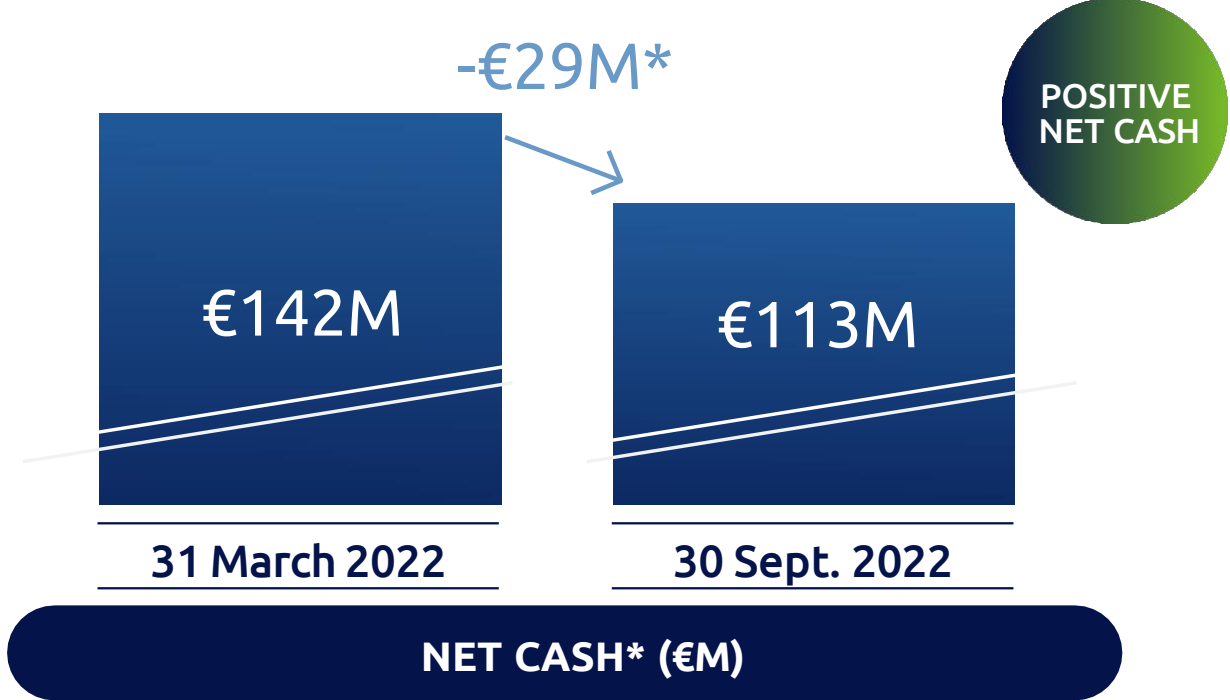
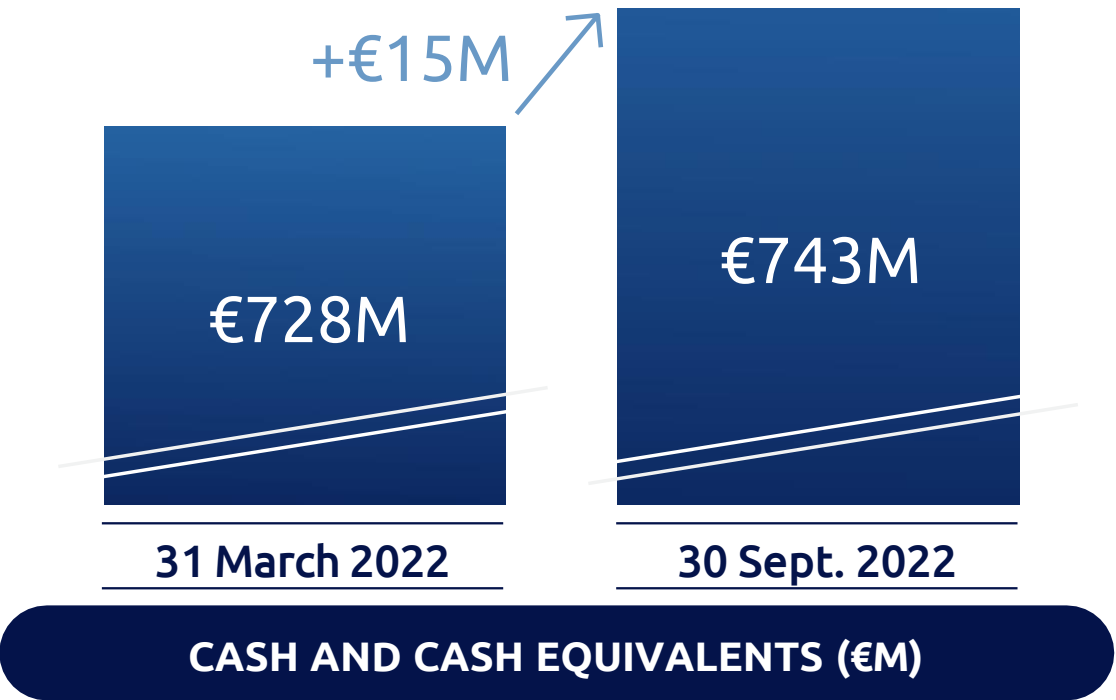
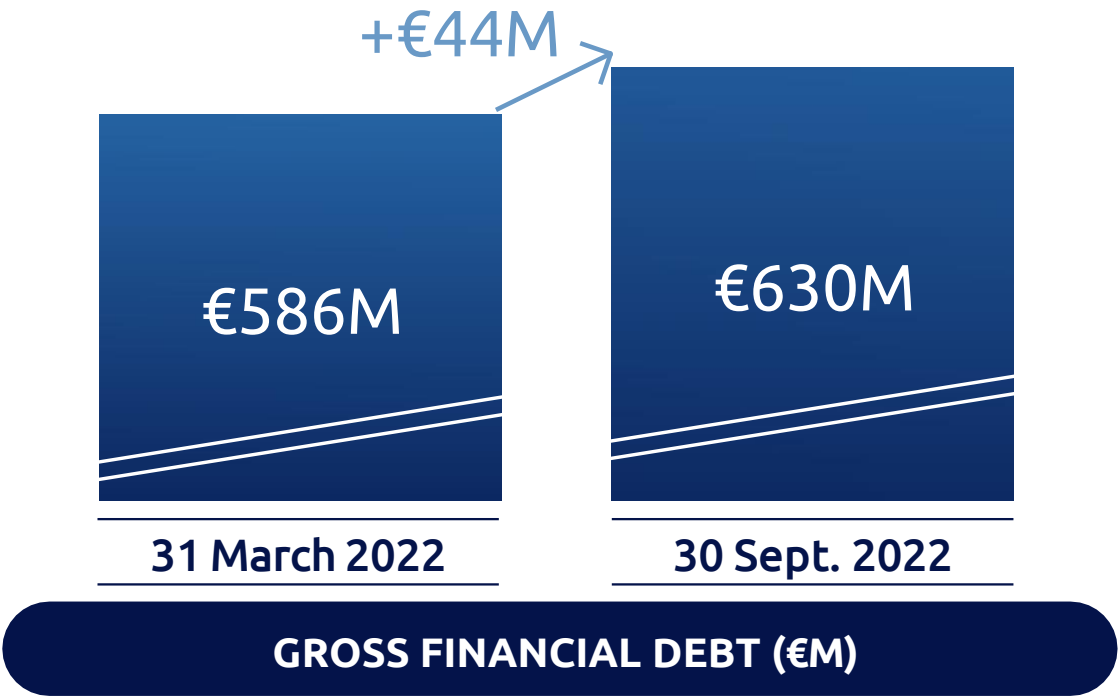
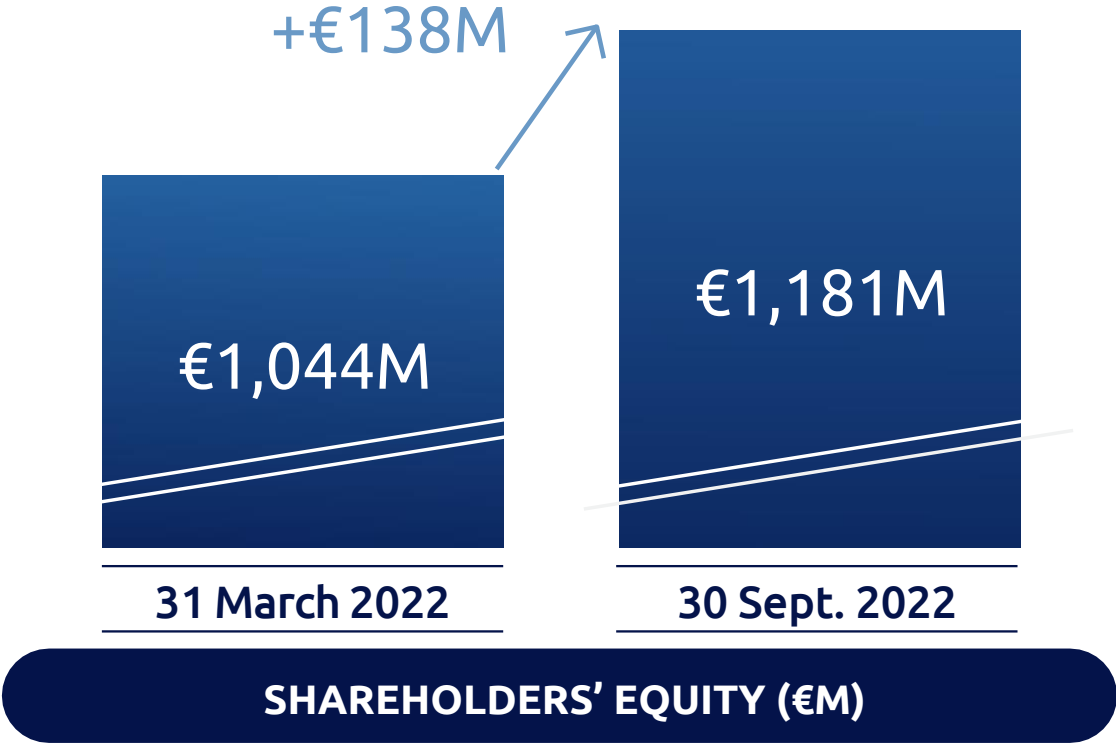
LIABILITIES AND EQUITY - in €M

	30 Sept. 2022	31 March 2022
Total equity	1,181	1,044
Long-term financial debt	530	518
Provisions and other non-current liabilities	84	79
Total non-current liabilities	614	597
Short-term financial debt	100	68
Trade payables	117	101
Other current liabilities	160	177
Total current liabilities	377	346
Total liabilities and equity	2,173	1,986

€44M increase in financial debt mainly reflects:

- €48M change of fair value financial derivatives (FX hedging)
- €4M interests related to OCEANES 2025
- Partially offset by €9M repayment of bank loans in Singapore

VERY HEALTHY FINANCIAL STRUCTURE AHEAD OF FUTURE GROWTH PLANS



* Excluding derivatives, positive net cash position of €186m, +€19m vs. 31 March 22



OUTLOOK – FY23 GUIDANCE CONFIRMED

~20% REVENUE GROWTH AT
CONSTANT FX RATE

ORGANIC GROWTH WILL CONTINUE TO BE DRIVEN BY ALL 3 END-MARKETS

- Ongoing 5G deployment
- Further recovery of automotive market
- Solid market trends for smart devices

EBITDA⁽¹⁾ MARGIN EXPECTED ~36%

STRONG OPERATING LEVERAGE OUTWEIGHS HIGHER COSTS

- Higher operating leverage
- Strong industrial performance and costs control
- Net exposure fully hedged at a €/€ rate of ~1.18
- Absorption of higher raw materials and energy costs

~€260M CAPEX

CONTINUING CAPACITY INVESTMENT

- First investments in SiC tools (150 & 200mm) in Bernin 4
- 300mm SOI Refresh capacity in Bernin 4
- Further ramp-up of Singapore 300mm SOI facility to ultimately reach 1 million wafers (RF-SOI and FD-SOI) and add refresh and epitaxy capacity
- Investments for innovation (including capitalized R&D)

(1) EBITDA margin = Electronics EBITDA (EBITDA from continuing operations) / Revenue



H1'23 FINANCIAL RESULTS

THANK YOU